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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JJ	AA	5 652042	7/29/97	KAWAKITA ETAL	428	209	
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

JJ	AR	R LASKY, "NEW PCB TECHNOLOGIES EMERGE FOR HIGH-DENSITY INTERCONNECT" ELECTRONIC PACKAGING AND PRODUCTION, APRIL 1998, PAGES 75-78
JJ	AS	HANG ET AL, "DEVELOPMENT OF HIGH CONDUCTIVITY LEAD(Pb)-FREE CONDUCTIVE ADHESIVES" IEEE TRANSACTIONS ON COMPONENTS, MANUFACTURING AND TECHNOLOGY, PART A, VOL 21, NO 1, MARCH 1998, PAGES 18-22
JJ	AT	HANG ET AL, "DEVELOPMENT OF LOW COST, LOW TEMPERATURE CONDUCTIVE ADHESIVES", PROCEEDINGS OF THE 48TH ELECTRONIC COMPONENTS & TECHNOLOGY CONFERENCE, SEATTLE, WASH., MAY 1998, PAGES 1031-1035

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Jonathan Johnson

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JJ	AU	GONZALEZ ET AL, "EPOXY-BASED AQUEOUS-PROCESSABLE PHOTODIETRIC DRY FILM AND CONDUCTIVE VIA PLUG FOR PCB BUILDUP AND IC PACKAGING," PROC. 48TH ELECTRONIC COMPONENTS TECH. CONF., SEATTLE, WASH., NOV. 1998, P.139-143
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